AMENDMENTS TO THE CLAIMS

1-22. (cancelled)

- 5 23. (currently amended): A light emitting diode having an adhesive layer and a reflective layer, comprising at least:
 - a substrate;
 - a reflective layer formed over the substrate;
 - a first reaction layer formed over said reflective layer;
- a transparent adhesive layer formed over said first reaction layer;
 - a second reaction layer formed over said transparent adhesive layer;
 - and an LED stack formed over said second reaction layer;

wherein at least one each of the first and second reaction layers is formed to enhance an adhesion provided by the transparent adhesive layer;

wherein said transparent adhesive layer comprises at least a material selected from the group consisting of polyimide (PI), benzocyclobutene (BCB), and perfluorocyclobutane (PFCB); and wherein each said first and second reaction layers comprises at least a material selected from the group consisting of SiNx, Ti, and Cr.

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- 24. (currently amended): A light emitting diode having an adhesive layer and a reflective layer according to claim 23, further comprising a transparent conductive layer between said second reaction layer and said LED stack.
- 25 25. (currently amended): A light emitting diode having an adhesive-layer and areflective layer according to claim 23, wherein said reflective layer is a reflective metal layer.
 - 26. (cancelled)

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27. (currently amended): A light emitting diode having an adhesive layer and a reflective layer according to claim 25, wherein said reflective metal layer

comprises at least a material selected from the group consisting of In, Sn, Al, Au, Pt, Zn, Ag, Ti, Pb, Pd, Ge, Cu, AuBe, AuGe, Ni, PbSn, and AuZn.

28-43. (cancelled)

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- 44. (currently amended): A light emitting diode having an adhesive layer and a reflective layer, comprising at least:
 - a reflective means;
 - a first reaction layer formed over said reflective means;
- a transparent adhesive layer formed over said first reaction layer;
 - a second reaction layer formed over said transparent adhesive layer; and
 - an LED stack formed over said second reaction layer;

wherein the first and second reaction layers enhance adhesion provided by the transparent adhesive layer,

wherein said transparent adhesive layer comprises at least a material selected from the group consisting of polyimide (PI), benzocyclobutene (BCB), and perfluorocyclobutane (PFCB); and wherein each said first and second reaction layers comprises at least a material selected from the group consisting of SiNx, Ti, and Cr.

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- 45. (currently amended): A light emitting diode having an adhesive layer and a reflective layer, comprising at least:
 - a substrate;
 - a reflective layer disposed on the substrate;
- a first reaction layer formed on said reflective layer;
 - a transparent adhesive layer formed directly on said first reaction layer, said first reaction layer adhering to the transparent adhesive layer;
 - a second reaction layer formed directly on said transparent adhesive layer, said second reaction layer adhering to the transparent adhesive layer; and
- an LED stack formed over said second reaction layer,

wherein said transparent adhesive layer comprises at least a material selected from the group consisting of polyimide (PI), benzocyclobutene (BCB), and perfluorocyclobutane (PFCB); and wherein each said first and second reaction layers comprises at least a material selected from the group consisting of SiNx, Ti, and Cr.

- 5 46. (cancelled)
 - 47. (currently amended): A light emitting diode having an adhesive layer and a reflective layer according to claim 45, further comprising a transparent conductive layer between said second reaction layer and said LED stack.

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- 48. (currently amended): A light emitting diode having an adhesive layer and a reflective layer according to claim 45, wherein said reflective layer is a reflective metal layer.
- 49. (currently amended): A light emitting diode having an adhesive layer and a reflective layer according to claim 48, wherein said reflective metal layer comprises at least a material selected from the group consisting of In, Sn, Al, Au, Pt, Zn, Ag, Ti, Pb, Pd, Ge, Cu, AuBe, AuGe, Ni, PbSn, and AuZn.
- 20 50-51. (cancelled)